ASSOCIATION CONNE	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1					Form Type Distribute	*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information								
Supplier Info	ormation														
Company name* Company unique ID				que ID		Unique ID Authority					Response Date*				
nsemi											2025-07-05				
ontact Name			Title - Contact				Phone - Contact*					Email - Contact*			
Product-Env-St	tewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized Rep	presentative*		Title - Representative				Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Envir	oduct Enviro Compliance NA					Product-Env-Stewards@onsemi.com				m		
Requ	Requester Item Number Mfr Iten		Number Mfr Item Name			Effective Dat	te V	ersion 1	Manufacturing Site		V	/eight*	UOM	Unit Type	
		AR0221S 0-DRBR	R2C00SUEA	2MP 1/2 CIS SO			2025-07-05		1	MY5		2	68.19	mg	Each
Ianufacturi	ing Proccess Information	n													
Terminal Plating / Grid Array Material T		al Te	erminal Base A	al Base Alloy J-STD-020 MSI		L Rating	Peak Pro	Peak Process Body Temperatu		ure Max Time at Peak Tempera		Temperatu	re Num	ber of Reflow Cy	cles
SnAg	gCu	С	U Alloy		4		260		С	30		second	ls 3		
omments															
or more inform	nation regarding material con	position p	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the
Supplier Digital Signature Ra	stislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	43.2	mg		Misc.	proprietary data	-	0.1642	mg
			Supplier	Silicon (Si)	7440-21-3		42.6082	mg
			Supplier	Aluminum (Al)	7429-90-5		0.4277	mg
Die Attach	3.73	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		1.3988	mg
			Supplier	Ethylene Glycol	107-21-1		0.0373	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.1119	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.7833	mg
			Supplier	Formaldehyde Polymer	9003-36-5		1.3988	mg
Imaging Lens	37.97	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		1.9984	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		1.9984	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		0.2001	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		1.9984	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		1.9984	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		1.9984	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		27.7781	mg
Lid Attach	1.95	mg	Supplier	2-phenoxy ethyl acrylate	48145-04-6		0.8775	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.39	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.2438	mg
			Supplier	Acrylate Oligomer	Proprietary Data		0.0098	mg
			Supplier	Curative	Proprietary Data		0.039	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.39	mg
Mold Compound-Black	87.47	mg		Phenolic Resin	proprietary data		13.1205	mg
			Supplier	Oxirane	39817-09-9		13.1205	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		2.6241	mg
			Supplier	Carbon Black (C)	1333-86-4		0.8747	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		55.9808	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.7494	mg
Solder Ball	40.84	mg	Supplier	Silver (Ag)	7440-22-4		1.2252	mg
			Supplier	Tin (Sn)	7440-31-5		39.4106	mg
			Supplier	Copper (Cu)	7440-50-8		0.2042	mg
Substrate and Solder Mask	52.64	mg	Supplier	Bis(3-ethyl-5-methyl-4- maleimidophenyl)methane	105391-33-1		0.5896	mg

			Supplier	Fiber Glass (SiO2)	65997-17-3	6.8221	mg
			Supplier	Zinc (Zn)	7440-66-6	0.079	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6	1.2265	mg
			Supplier	Cyanic acid (1-methylethylidene)di-4,1- phenylene ester homopolymer	25722-66-1	0.5896	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9	0.3053	mg
			Supplier	Chromium (Cr)	7440-47-3	0.0053	mg
			Supplier	Acetophenone Derivative	Proprietary Data	1.8371	mg
			Supplier	Carbon Black (C)	1333-86-4	0.3053	mg
			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.3053	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2	6.3168	mg
			В	Nickel (Ni)	7440-02-0	0.7422	mg
			Supplier	Gold (Au)	7440-57-5	0.0263	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	3.6795	mg
			Supplier	Formaldehyde Polymer	9003-36-5	0.5896	mg
			Supplier	Copper (Cu)	7440-50-8	19.7189	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	9.5015	mg
Wire Bond - Au	0.39	mg	Supplier	Gold (Au)	7440-57-5	0.39	mg